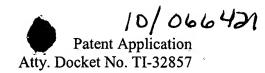
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ABSTRACT

The present invention discloses a method and system of wire bonding a semiconductor die to a lead using interposer pads. The use of disclosed embodiment of the present invention permits combined bonding wire lengths of up to 8 mm while reducing wire sweep, wire spacing violations and wire shorts.